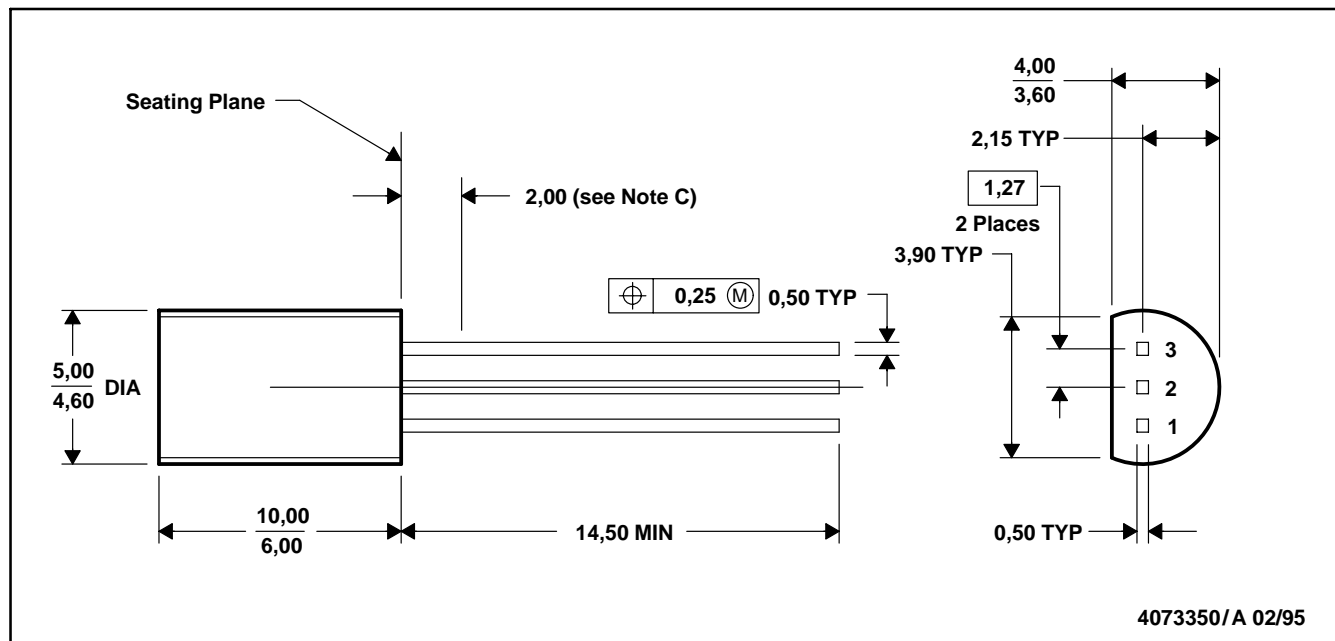


LPB (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Lead dimensions are not controlled within this area.

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